

Materials List for:

Laser-induced Forward Transfer for Flip-chip Packaging of Single Dies

Kamal S. Kaur¹, Geert Van Steenberge¹

¹Center for Microsystems Technology (CMST), Ghent University-imec

Correspondence to: Kamal S. Kaur at Kaur.Kamalpreet@elis.ugent.be

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Materials

Name	Company	Catalog Number	Comments
Laser source	3D MicroMac (3DMM)	2912-295	
Photodetector	Newport	818 series	
Source measurement unit	Keithley	2401	
Power meter	Newport	1930	
Underfill	Norlands	NOA 86	
UV lamp	Omnigure	Series 1000 UV	
Probe station	Cascade Microtech	model 42	
Flip-chip bonder	Dr. Tresky	T-320 X	